

## Overview

The Wave2Wave 400G QSFP-DD LR4 Transceiver is a long-reach optical module designed for modern data center, cloud, and carrier networks that require reliable 400G performance over single-mode fiber. Using a 4-lane CWDM architecture and compliant with QSFP-DD MSA and 100G Lambda MSA, it supports transmission distances up to 10 km with strong signal integrity.

Equipped with cooled EML lasers, PIN receivers, and an 8x53.125G PAM4 (400GAUI-8) electrical interface, the module delivers efficient 400G optical transport with low power consumption and stable thermal performance. Fully compliant with IEEE 802.3bs, it ensures seamless interoperability across next-generation switching and routing platforms within a 0°C to 70°C operating range.



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### Features & Benefits

- Compliant with QSFP-DD MSA Type 2, 100G Lambda MSA 400G LR4, and IEEE 802.3bs.
- Supports 400Gb/s transmission over 4 CWDM lanes up to 10 km on SMF.
- Utilizes cooled EML transmitters and PIN receivers for high stability and long-reach performance.
- Integrates 8x53.125G PAM4 electrical lanes (400GAUI-8) for seamless system compatibility.
- Efficient operation with a single +3.3V supply and ≤12W power consumption.
- Designed for reliable performance across 0–70°C commercial temperature range.
- Built with a duplex LC connector and fully RoHS compliant.

### Applications

- 400G Ethernet
- Data center and cloud interconnects
- Leaf-spine architectures
- Long-reach switching and routing links
- Core and metro optical transport
- High-capacity AI/ML and HPC networks

### Ordering information

Part Number	Transmitter	Output Power	Receiver	Receive power	Reach	Temp	DDM	RoHS
77-QD040-LR4	Cooled EML	-2.7 to +5.1dBm	PIN	-9 to +5.1dBm	10km	0 ~ 70°C	Available	Compliant

### Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Unit	Notes
Storage Temperature	T <sub>S</sub>	-40	85	°C	
Relative Humidity	RH	5	85	%	
Supply Voltage	V <sub>CC</sub>	-0,5	3,6	V	

Recommended Operating Conditions						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Operating Case Temperature (Commercial)	Tc	0		70	°C	
Supply Voltage	Vcc	3.135	3.3	3.465	V	
Electrical interface Data Rate Each Lane (PAM4)			26.5625		GBd	
Link Distance	D	0.002		10	km	

Transmitter Optical Characteristics						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
PAM4 Signaling rate, each lane			53.125 ± 100 ppm		GBd	
Lane Wavelengths (range)	λ0	1264.5	1271	1277.5	nm	
	λ1	1284.5	1291	1297.5		
	λ2	1304.5	1311	1317.5		
	λ3	1324.5	1331	1337.5		
Side-mode suppression ratio	SMSR	30			dB	
Total average launch power				11	dBm	
Average launch power, each lane	Pa	-2.7		5.1	dBm	1
Outer Optical Modulation Amplitude, each lane	OMAouter	0.3		4.4	dBm	2
Difference in launch power between any two lanes (OMAouter)				4	dB	
Transmitter and dispersion penalty eye closure for PAM4 (TDECQ), each lane	TDECQ			3.9	dB	
Average launch power of OFF transmitter, each lane	Poff			-16	dBm	
Extinction ratio	ER	3.5			dB	
Transmitter transition time				17	ps	
RIN17.1 OMA	RIN			-136	dB/Hz	
Optical return loss tolerance	TOL			15.6	dB	
Transmitter reflectance	TRL			-26	dB	3

#### NOTES:

1. Average launch power, each lane (min) is informative and not the principal indicator of signal strength. A transmitter with launch power below this value cannot be compliant; however, a value above this does not ensure compliance.
2. For TDECQ < 1.4dB , OMAouter > 0.3 ; 1.4dB≤TDECQ≤3.9dB, OMAouter > -1.1+TDECQ
3. Transmitter reflectance is defined looking into the transmitter.

Receiver Optical Characteristics						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
PAM4 Signaling rate, each lane			53.125 ± 100 ppm		GBd	
Lane Wavelengths	λ0	1264.5		1277.5	nm	
	λ1	1284.5		1297.5	nm	
	λ2	1304.5		1317.5	nm	
	λ3	1324.5		1337.5	nm	
Damage threshold, each lane		6.1			dBm	1
Average receive power, each lane		- 9		5.1	dBm	2
Receive power, each lane (OMAouter)				4.4	dBm	
Difference in receive power between any two lanes (OMAouter)				4.3	dB	
Receiver reflectance				-26	dB	
Receiver sensitivity (OMAouter), each lane				Equation (1)	dBm	3
Stressed receiver sensitivity (OMAouter), each lane				-4.3	dBm	4
Conditions of stressed receiver sensitivity test: Stressed eye closure for PAM4 (SECQ), lane under test SECQ – 10*log10(Ceq), lane under test (max)			3.9		dB	5
OMAouter of each aggressor lane			-0.4		dB	
					dBm	

**NOTES:**

1. The receiver shall be able to tolerate, without damage, continuous exposure to an optical signal having this average power level. The receiver does not have to operate correctly at this input power.
2. Average receive power, each lane (min) is informative and not the principal indicator of signal strength. A received power below this value cannot be compliant; however, a value above this does not ensure compliance.
3. Receiver sensitivity (OMAouter), each lane (max) is informative and is defined for a transmitter with a value of SECQ up to 3.4 dB. Receiver Sensitivity should meet Equation (1), which is illustrated in Figure 1.

$$RS = \max(-4.6, SECQ-6.0) \text{ dBm} \quad (1)$$

4. Measured with conformance test signal at TP3 for the BER equal to 2.4E-4
5. Ceq is a coefficient defined in IEEE Std 802.3-2018 clause 121.8.5.3 which accounts for reference equalizer noise enhancement.

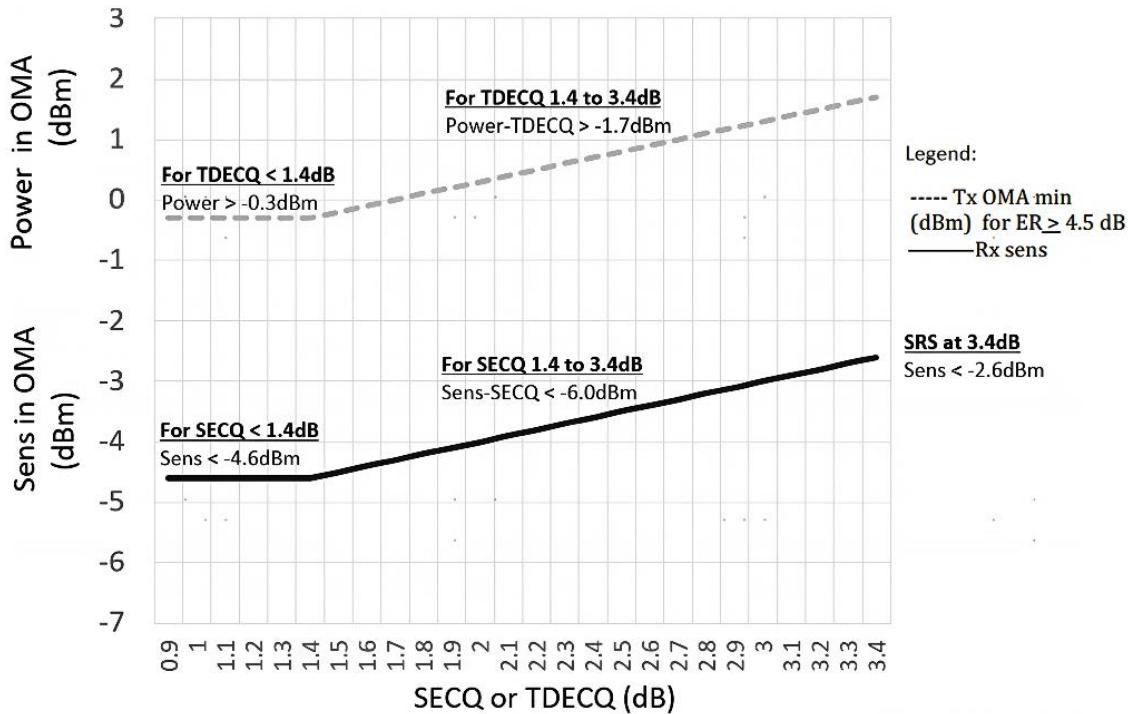


Figure 1. Illustrated of receiver sensitivity mask for 400G LR4

Electrical Characteristics						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Module Supply Current	Icc			3636	mA	
Power Dissipation	PD			12	W	
Transmitter						
Signaling Rate, each Lane		26.5625±100ppm			GBd	
Input Differential Impedance	ZIN		100		Ω	
Differential Data Input Swing	VIN, P-P	210		900	mVP-P	1
Differential Termination Mismatch	TP1			10	%	
Differential Input Return Loss	TP1	IEEE 802.3 2015 Equation (83E-5)			dB	
Differential to Common Mode Input Return Loss	TP1	IEEE 802.3-2015 Equation (83E-6)			dB	
Module Stressed Input Test	TP1a	See IEEE 802.3bs 120E.3.4.1				2
Single-ended voltage tolerance range	TP1a	-0.4 to 3.3			V	
DC common mode voltage	TP1	-350		2850	mV	3
Receiver						
Signaling Rate, each lane	TP4	26.5625 ± 100 ppm			GBd	
Output Differential Impedance	TP4		100		Ω	
Differential termination mismatch	TP4			10	%	
Differential Data Output Swing	TP4			900	mVP-P	
AC Common Mode Output Voltage, RMS	TP4			17.5	mV	
Differential output return loss	TP4	IEEE 802.3-2015 Equation (83E-2)				
Common to differential mode conversion	TP4	IEEE 802.3-2015 Equation (83E-3)				
Near-end eye width, all 3 eyes	TP4		0.265		UI	
Near-end eye height, all 3 eyes	TP4		70		mV	
Far-end eye width, all 3 eyes	TP4		0.2		UI	
Far-end eye height, all 3 eyes	TP4		30		mV	
Far-end pre-cursor ISI ratio	TP4	-4.5		2.5	%	
Transition time	TP4	9.5			ps	
DC common mode voltage	TP1	-350		2850	mV	3

#### NOTES:

- With the exception to IEEE 802.3bs 120E.3.1.2 that the pattern is PRBS31Q or scrambled idle
- Meets BER specified in IEEE 802.3bs 120E.1.1
- DC common mode voltage generated by the host. Specification includes effects of ground offset voltage

## Pin Description

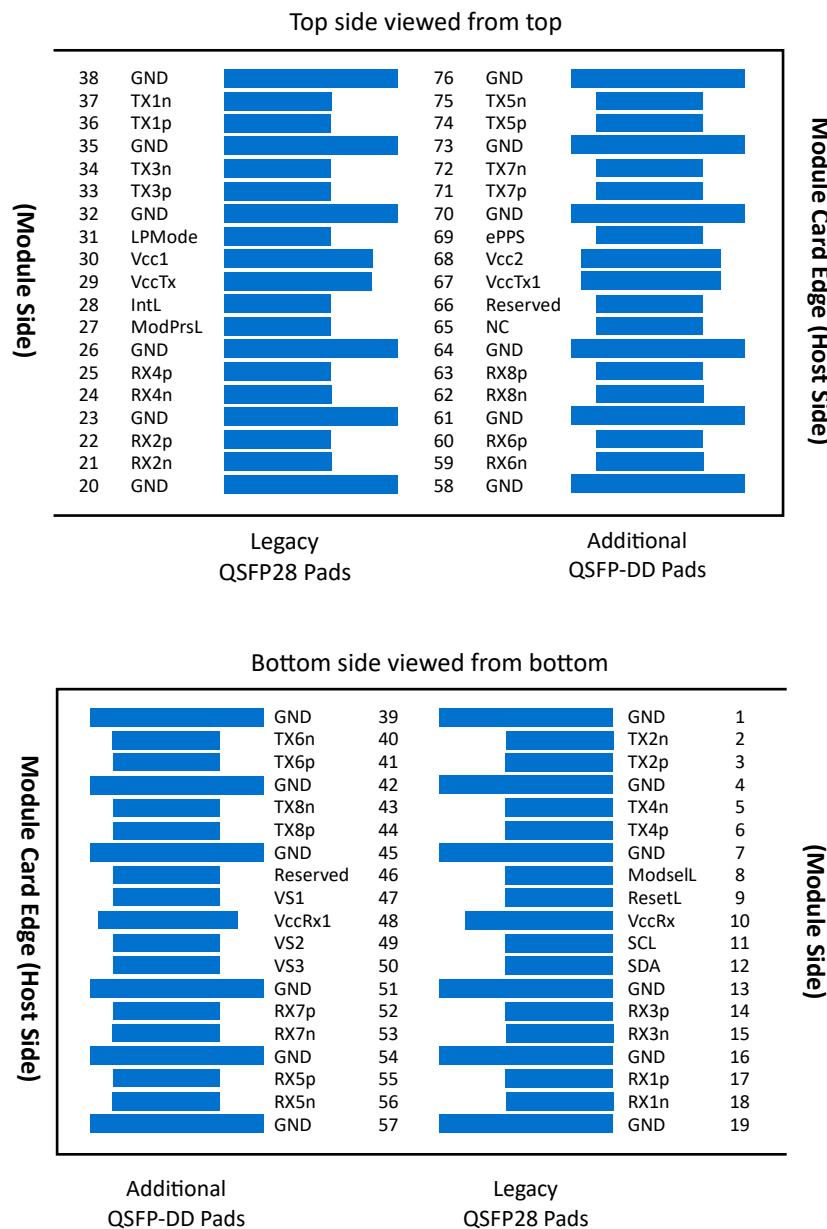


Figure 2. QSFP-DD pad assignment top view

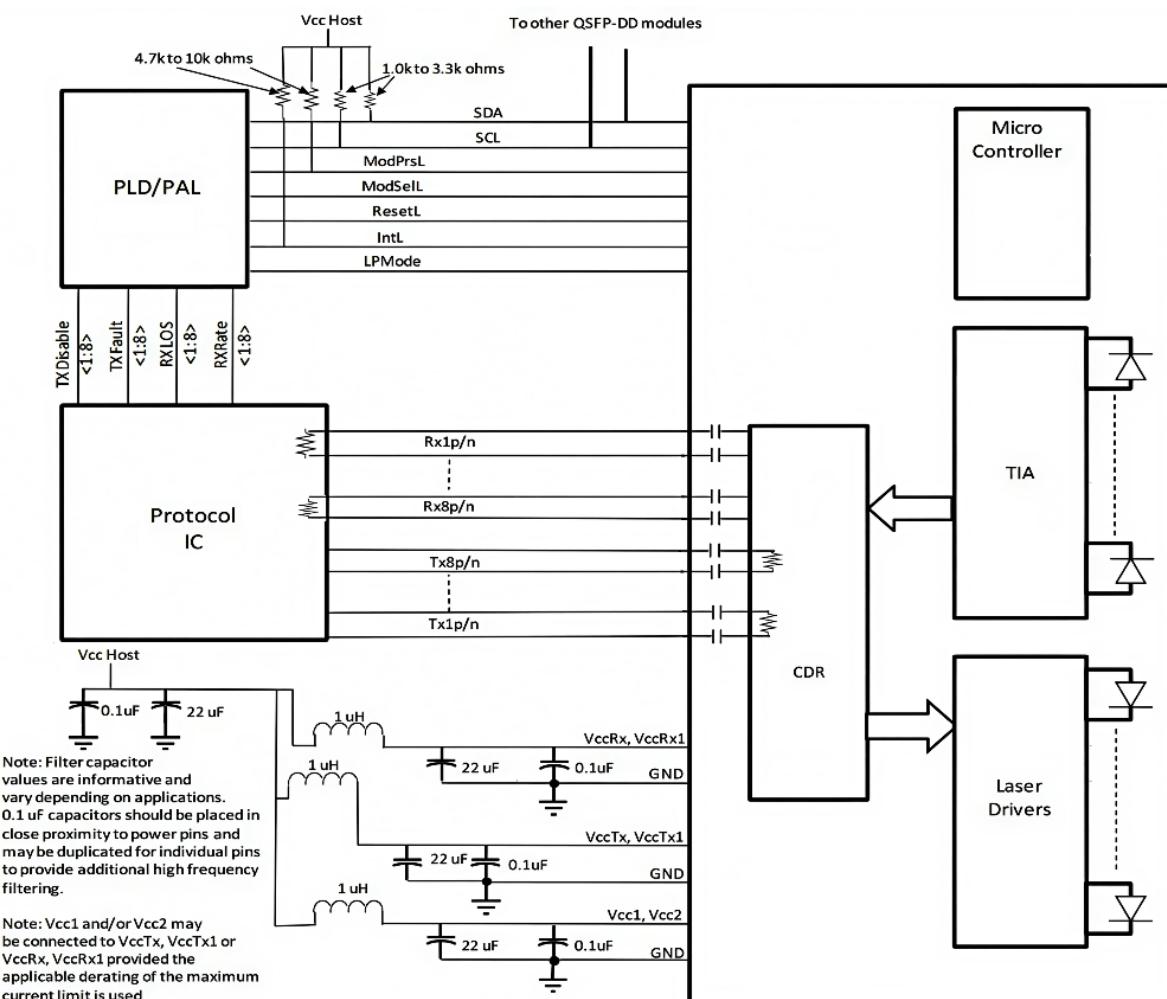
PIN Description					
Pin	Logic	Symbol	Name/Description	Plug Sequence	Notes
1		GND	Ground	1B	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3B	
3	CML-I	Tx2p	Transmitter Non-Inverted Data Input	3B	
4		GND	Ground	1B	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3B	
6	CML-I	Tx4p	Transmitter Non-Inverted Data Input	3B	
7		GND	Ground	1B	1
8	LVTTI-I	ModSelL	Module Select	3B	
9	LVTTI-I	ResetL	Module Reset	3B	
10		VccRx	+3.3V Power Supply Receiver	2B	2
11	LVCMOS-I/O	SCL	2-wire serial interface clock	3B	
12	LVCMOS-I/O	SDA	2-wire serial interface data	3B	
13		GND	Ground	1B	1
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3B	
15	CML-O	Rx3n	Receiver Inverted Data Output	3B	
16		GND	Ground	1B	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3B	
18	CML-O	Rx1n	Receiver Inverted Data Output	3B	
19		GND	Ground	1B	1
20		GND	Ground	1B	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3B	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3B	
23		GND	Ground	1B	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3B	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3B	
26		GND	Ground	1B	1
27	LVTTI-O	ModPrsL	Module Present	3B	
28	LVTTI-O	IntL	Interrupt	3B	
29		VccTx	+3.3V Power supply transmitter	2B	2
30		Vcc1	+3.3V Power supply	2B	2
31	LVTTI-I	LPMode	Low Power mode	3B	
32		GND	Ground	1B	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3B	
34	CML-I	Tx3n	Transmitter Inverted Data Input	3B	
35		GND	Ground	1B	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3B	
37	CML-I	Tx1n	Transmitter Inverted Data Input	3B	
38		GND	Ground	1B	1
39		GND	Ground	1A	1

## PIN Description (continued)

Pin	Logic	Symbol	Name/Description	Plug Sequence	Notes
40	CML-I	Tx6n	Transmitter Inverted Data Input	3A	
41	CML-I	Tx6p	Transmitter Non-Inverted Data Input	3A	
42		GND	Ground	1A	1
43	CML-I	Tx8n	Transmitter Inverted Data Input	3A	
44	CML-I	Tx8p	Transmitter Non-Inverted Data Input	3A	
45		GND	Ground	1A	1
46		Reserved	For future use	3A	3
47		VS1	Module Vendor Specific 1	3A	3
48		VccRx1	3.3V Power Supply	2A	2
49		VS2	Module Vendor Specific 2	3A	3
50		VS3	Module Vendor Specific 3	3A	3
51		GND	Ground	1A	1
52	CML-O	Rx7p	Receiver Non-Inverted Data Output	3A	
53	CML-O	Rx7n	Receiver Inverted Data Output	3A	
54		GND	Ground	1A	1
55	CML-O	Rx5p	Receiver Non-Inverted Data Output	3A	
56	CML-O	Rx5n	Receiver Inverted Data Output	3A	
57		GND	Ground	1A	1
58		GND	Ground	1A	1
59	CML-O	Rx6n	Receiver Inverted Data Output	3A	
60	CML-O	Rx6p	Receiver Non-Inverted Data Output	3A	
61		GND	Ground	1A	1
62	CML-O	Rx8n	Receiver Inverted Data Output	3A	
63	CML-O	Rx8p	Receiver Non-Inverted Data Output	3A	
64		GND	Ground	1A	1
65		NC	No Connect	3A	3
66		Reserved	For future use	3A	3
67		VccTx1	3.3V Power Supply	2A	2
68		Vcc2	3.3V Power Supply	2A	2
69	LVTTI-I	ePPS	Precision Time Protocol (PTP) reference clock input	3A	3
70		GND	Ground	1A	1
71	CML-I	Tx7p	Transmitter Non-Inverted Data Input	3A	
72	CML-I	Tx7n	Transmitter Inverted Data Input	3A	
73		GND	Ground	1A	1
74	CML-I	Tx5p	Transmitter Non-Inverted Data Input	3A	
75	CML-I	Tx5n	Transmitter Inverted Data Input	3A	
76		GND	Ground	1A	1

**NOTES:**

1. QSFP-DD uses common ground (GND) for all signals and supply (power). All are common within the QSFP-DD module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.
2. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 shall be applied concurrently. Requirements defined for the host side of the Host Card Edge Connector are listed in Table 8. VccRx, VccRx1, Vcc1, Vcc2, VccTx and VccTx1 may be internally connected within the module in any combination. For power classes 4 and above the module differential loading of input voltage pins must not result in exceeding pin current limits. The connector Vcc pins are each rated for a maximum current of 1000 mA.
3. All Vendor Specific, Reserved, No Connect and ePPS (if not used) pins may be terminated with 50 ohm to ground on the host. Pad 65 (No Connect) shall be left unconnected within the module. Vendor specific and Reserved pads shall have an impedance to GND that is greater than 10 kΩ and less than 100 pF.
4. Plug Sequence specifies the mating sequence of the host connector and module. The sequence is 1A, 2A, 3A, 1B, 2B, 3B. (see Figure 2 for pad locations) Contact sequence A will make, then break contact with additional QSFP-DD pads. Sequence 1A and 1B will then occur simultaneously, followed by 2A and 2B, followed by 3A and 3B

**Recommended peripheral circuit**


QSFP-DD Optical Module

Figure 3. Example QSFP-DD Host Board Schematic for Optical Modules

## Mechanical Specifications

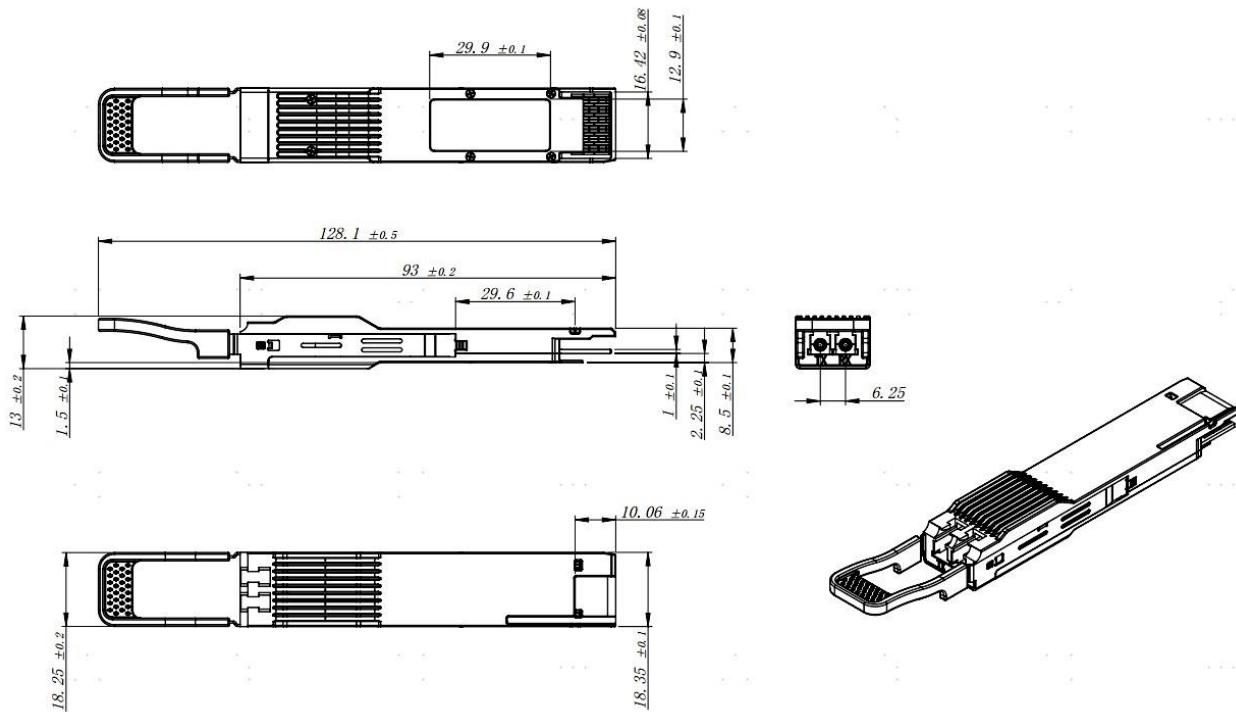


Figure 4. Outline Drawing